



N 沟道增强型场效应晶体管 N-CHANNEL MOSFET FHP4N65D/FHF4N65D/FHD4N65D

主要参数 MAIN CHARACTERISTICS

ID	4 A
VDSS	650 V
Rdson-typ (@Vgs=10V)	2.3 Ω
Qg-typ	14.5 nC

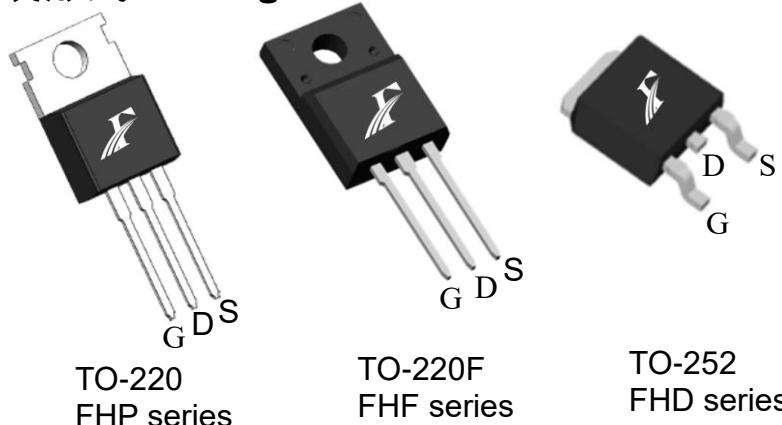
用途 APPLICATIONS

高频开关电源	High efficiency switch mode power supplies
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产品特性 FEATURES

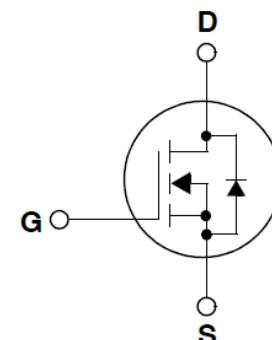
低栅极电荷	Low gate charge
低 Crss (典型值 4.2 pF)	Low Crss (typical 4.2 pF)
开关速度快	Fast switching
100% 经过雪崩测试	100% avalanche tested
100% 经过热阻测试	100% DVDS tested
100% 经过 Rg 测试	100% Rg tested
高抗 dv/dt 能力	Improved dv/dt capability
平面工艺	Plane process
RoHS 产品	RoHS product

封装形式 Package



绝对最大额定值 ABSOLUTE RATINGS (Tc=25°C)

等效电路 Equivalent Circuit



项目 Parameter	符号 Symbol	数值 Value		单位 Unit
		FHP/D4N65D	FHF4N65D	
最高漏极—源极直流电压 Drain-Source Voltage	VDS	650		V
连续漏极电流* Drain Current -continuous *	Id (Tc=25°C)	4		A
	Id (Tc=100°C)	2.5		A
最大脉冲漏极电流 (注 1) Drain Current – pulse (note 1)	Idm	16		A
最高栅源电压 Gate-Source Voltage	VGS	±30		V
单脉冲雪崩能量 (注 2) Single Pulsed Avalanche Energy (note 2)	EAS	45		mJ
雪崩电流 (注 1) Avalanche Current (note 1)	IAR	3		A
重复雪崩能量 (注 1) Repetitive Avalanche Current (note 1)	EAR	10		mJ
二极管反向恢复最大电压变化速率 (注 3) Peak Diode Recovery dv/dt (note 3)	dv/dt	5.0		V/ns
耗散功率 Power Dissipation	Pd (TC=25°C)	75	30	W
	-Derate above 25°C	0.6	0.24	W/°C
最高结温及存储温度 Operating and Storage Temperature Range	Tj, Tstg	150, -55 to 150		°C
引线最高焊接温度 Maximum Lead Temperature for Soldering Purposes	Tl	300		°C

*漏极电流由最高结温限制

*Drain current limited by maximum junction temperature

电特性 ELECTRICAL CHARACTERISTICS

项目 Parameter	符号 Symbol	测试条件 Tests conditions	最小 Min	典型 Typ	最大 Max	单位 Units	
关态特性 Off -Characteristics							
漏一源击穿电压 Drain-Source Voltage	BVDSS	ID=250μA, VGS=0V	650	-	-	V	
击穿电压温度特性 Breakdown Voltage Temperature Coefficient	ΔBVDSS/Δ TJ	ID=250μA, referenced to 25°C	-	0.65	-	V/°C	
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	IDSS	VDS=650V, VGS=0V, TC=25°C	-	-	1	μA	
		VDS=520V, TC=125°C	-	-	100	μA	
栅极体漏电流 Gate-body leakage current	IGSS (F/R)	VDS=0V, VGS =±30V	-	-	±100	nA	
通态特性 On-Characteristics							
阈值电压 Gate Threshold Voltage	VGS(th)	VDS = VGS, ID=250μA	2.3	3.1	3.5	V	
静态导通电阻 Static Drain-Source On-Resistance	RDS(ON)	VGS =10V , ID=2A	-	2.3	2.6	Ω	
正向跨导 Forward Transconductance	gfs	VDS = 15V, ID=4A (note 4)	-	3.5	-	S	
动态特性 Dynamic Characteristics							
输入电容 Input capacitance	Ciss	VDS=25V, VGS =0V, f=1.0MHz	-	557	-	pF	
输出电容 Output capacitance	Coss		-	60	-		
反向传输电容 Reverse transfer capacitance	Crss		-	4.2	-		
开关特性 Switching Characteristics							
栅电阻 Gate Resistance	Rg	f=1.0MHz, VDS OPEN	-	2.8	-	Ω	
延迟时间 Turn-On delay time	td(on)		-	14	-	ns	
上升时间 Turn-On rise time	tr		-	16	-	ns	
延迟时间 Turn-Off delay time	td(off)		-	32	-	ns	
下降时间 Turn-Off Fall time	tf		-	11	-	ns	
栅极电荷总量 Total Gate Charge	Qg		-	14.5	-	nC	
栅一源电荷 Gate-Source charge	Qgs	VDS =520V , ID=4A , VGS =10V (note 4, 5)	-	3.2	-	nC	
栅一漏电荷 Gate-Drain charge	Qgd		-	6.5	-	nC	
漏一源二极管特性及最大额定值 Drain-Source Diode Characteristics and Maximum Ratings							
正向最大连续电流 Maximum Continuous Drain -Source Diode Forward Current	Is		-	-	4	A	
正向最大脉冲电流 Maximum Pulsed Drain-Source Diode Forward Current	ISM		-	-	16	A	
正向压降 Drain-Source Diode Forward Voltage	VSD	VGS=0V, Is=4A	-	-	1.2	V	
反向恢复时间 Reverse recovery time	trr	VGS=0V, Is=4A ,dI/dt=100A/μs (note 4)	-	256	-	ns	
反向恢复电荷 Reverse recovery charge	Qrr		-	1.21	-	μC	

热特性 THERMAL CHARACTERISTIC

项目 Parameter	符号 Symbol	FHP/D4N65D	FHF4N65D	单位 Unit
结到管壳的热阻 Thermal Resistance, Junction to Case	R _{th(j-c)}	1.67	4.17	°C/W
结到环境的热阻 Thermal Resistance, Junction to Ambient	R _{th(j-A)}	62.5	62.5	°C/W

注释:

- 1: 脉冲宽度由最高结温限制
- 2: L=10mH, IAS=3A, VDS=50V, RG=25 Ω, 起始结温 TJ=25°C
- 3: ISD ≤4A, di/dt ≤100A/μs, VDD≤BV_{DSS}, 起始结温 TJ=25°C
- 4: 脉冲测试: 脉冲宽度 ≤300μs, 占空比≤2%
- 5: 基本与工作温度无关

Notes:

- 1: Pulse width limited by maximum junction temperature
- 2: L=10mH, IAS=3A, VDS=50V, RG=25 Ω ,Start TJ=25°C;
- 3: ISD ≤4A,di/dt ≤100A/μs,V_{DD}≤BV_{DSS}, Starting TJ=25 °C
- 4: Pulse Test: Pulse Width ≤300μs,Duty Cycle≤2%
- 5: Essentially independent of operating temperature

特性曲线 (ELECTRICAL CHARACTERISTICS (curves))

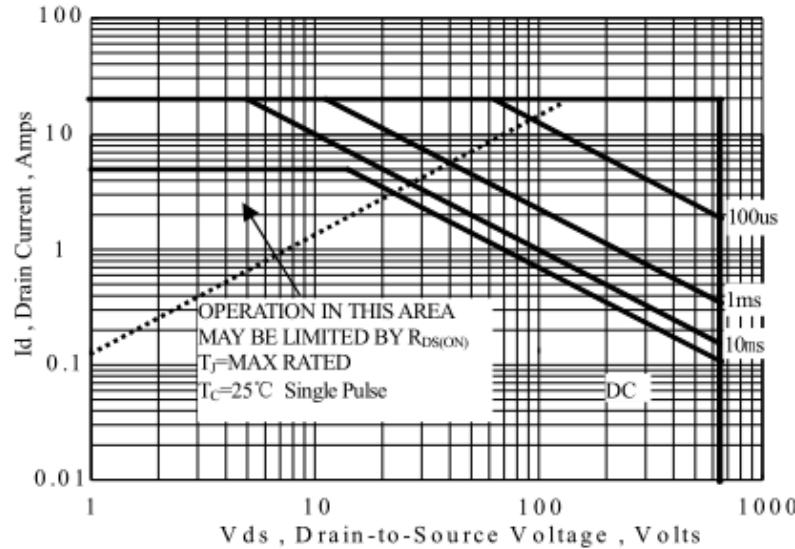


Figure 1 Maximum Forward Bias Safe Operating Area

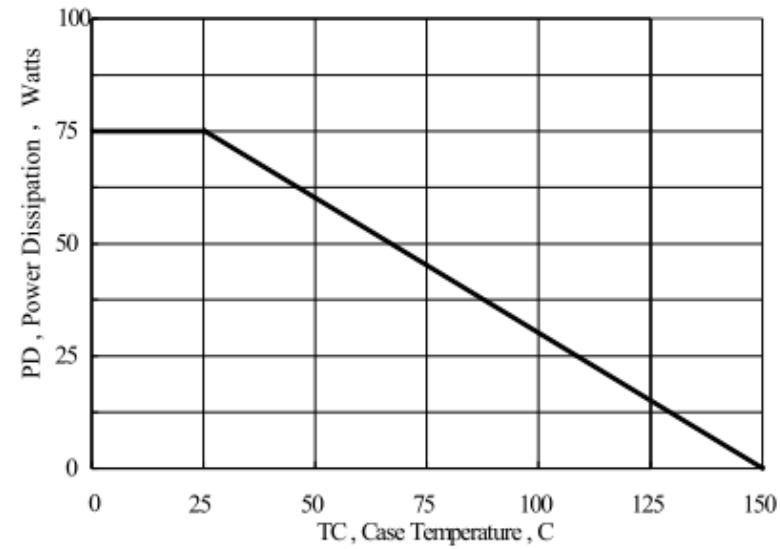


Figure 2 Maximum Power Dissipation vs Case Temperature

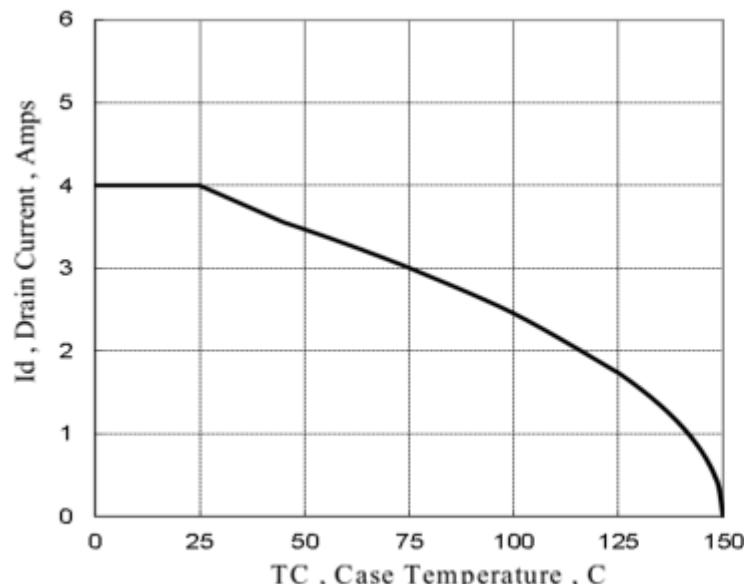


Figure 3 Maximum Continuous Drain Current vs Case Temperature

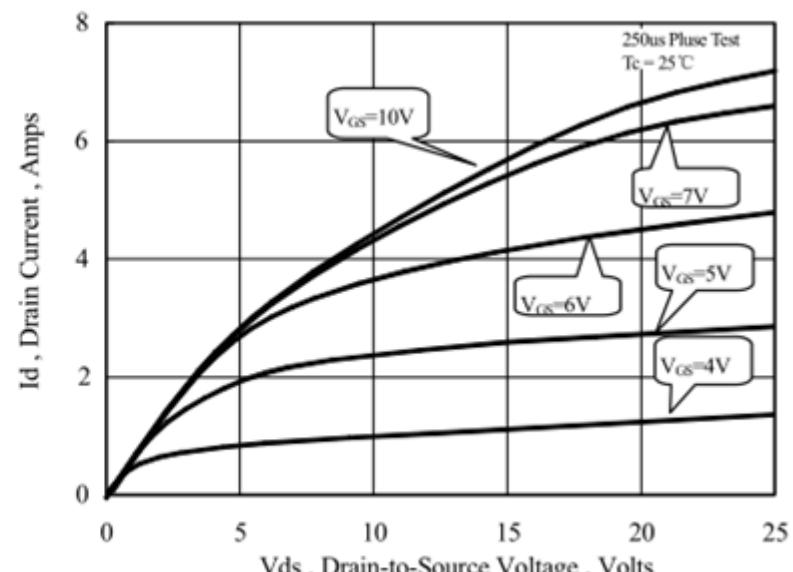


Figure 4 Typical Output Characteristics

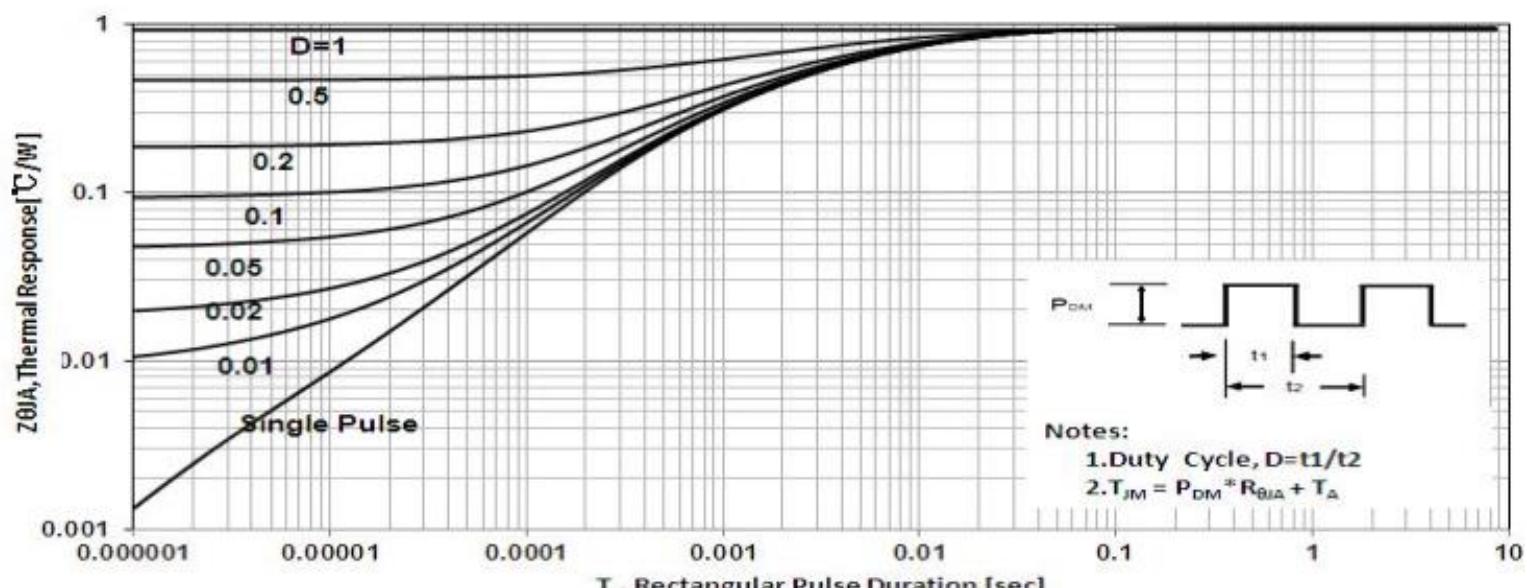


Figure 5 Maximum Effective Thermal Impedance, Junction to Case

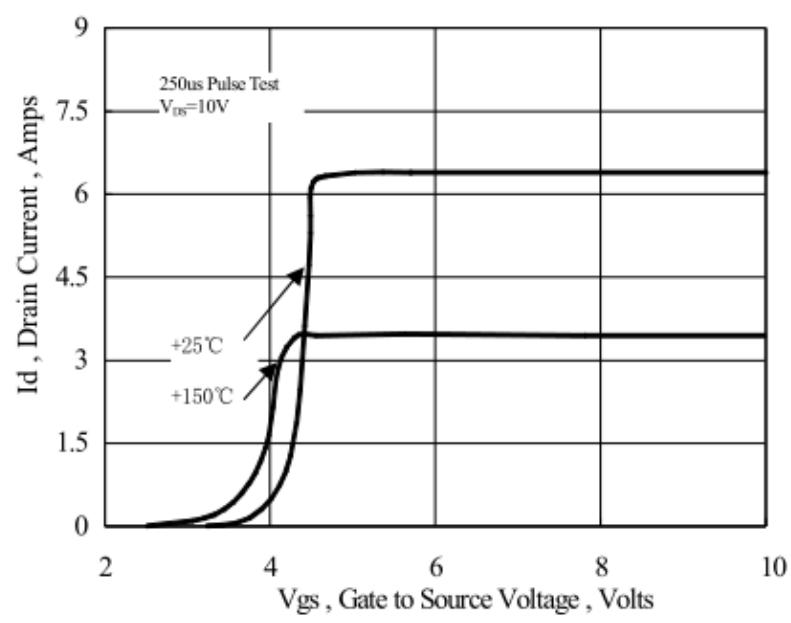


Figure 6 Typical Transfer Characteristics

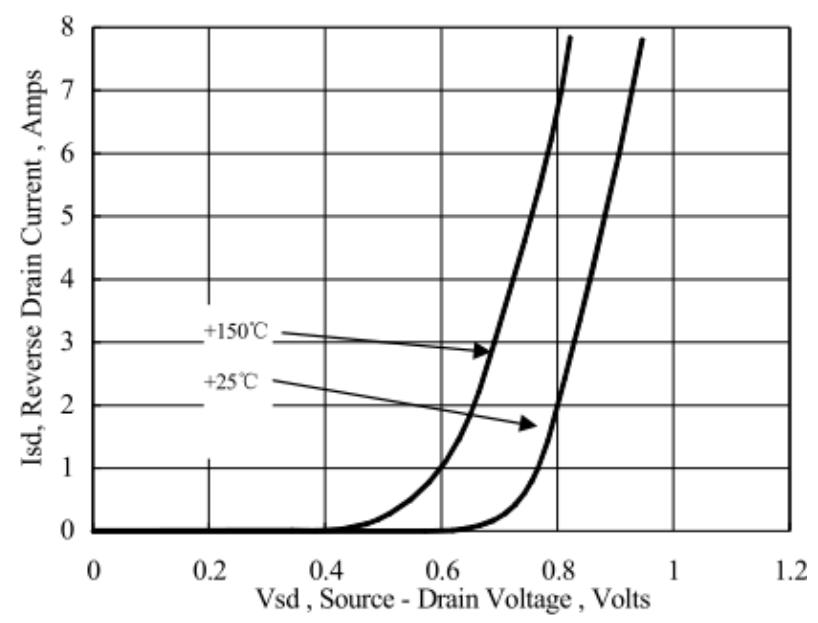


Figure 7 Typical Body Diode Transfer Characteristics

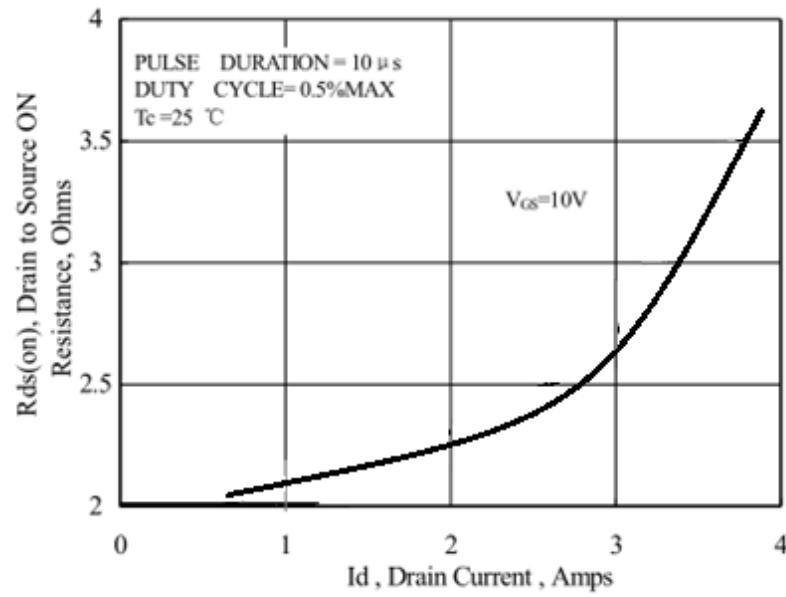


Figure 8 Typical Drain to Source ON Resistance vs Drain Current

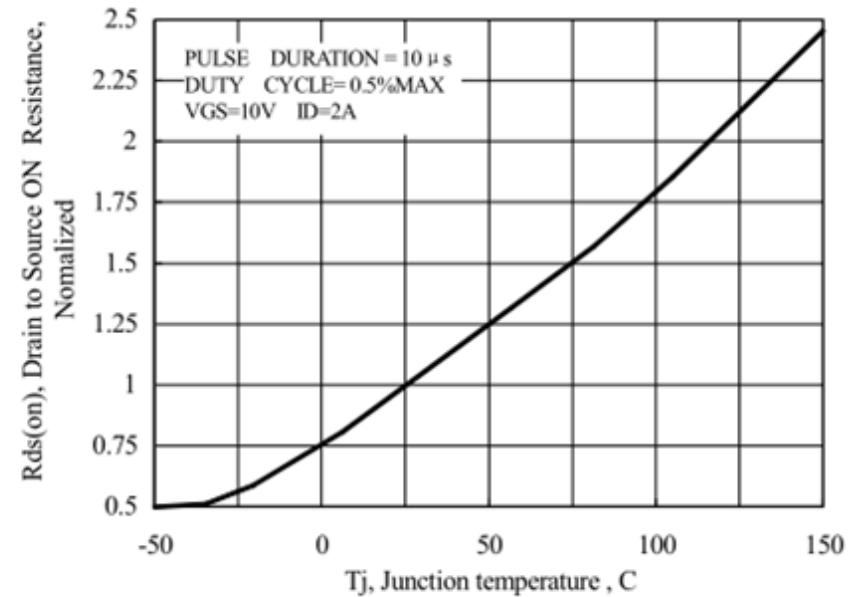


Figure 9 Typical Drian to Source on Resistance vs Junction Temperature

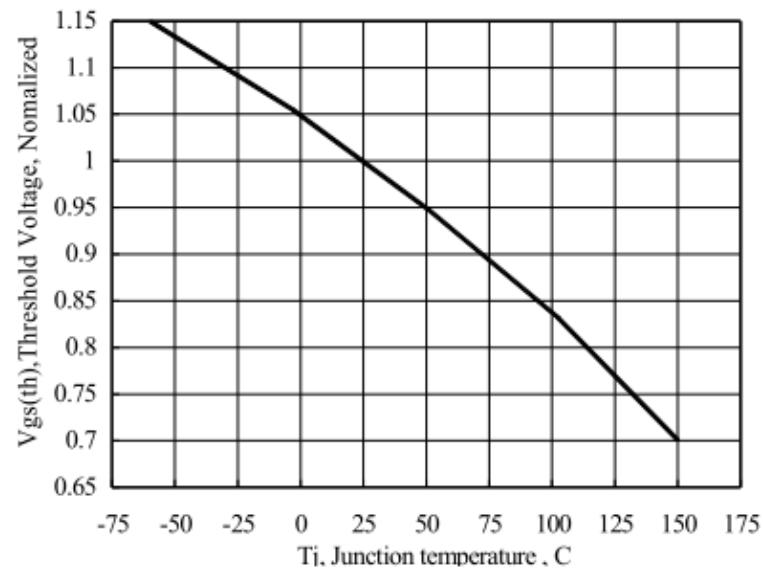


Figure 10 Typical Threshold Voltage vs Junction Temperature

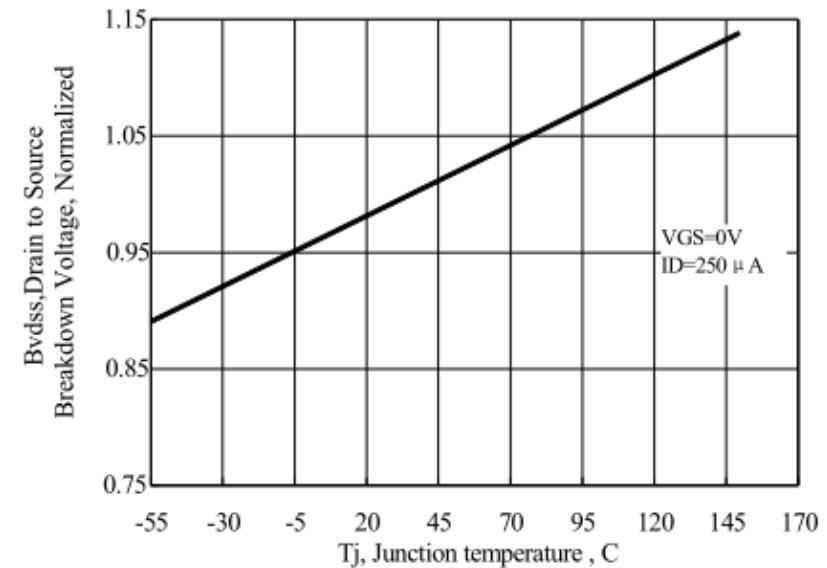


Figure 11 Typical Breakdown Voltage vs Junction Temperature

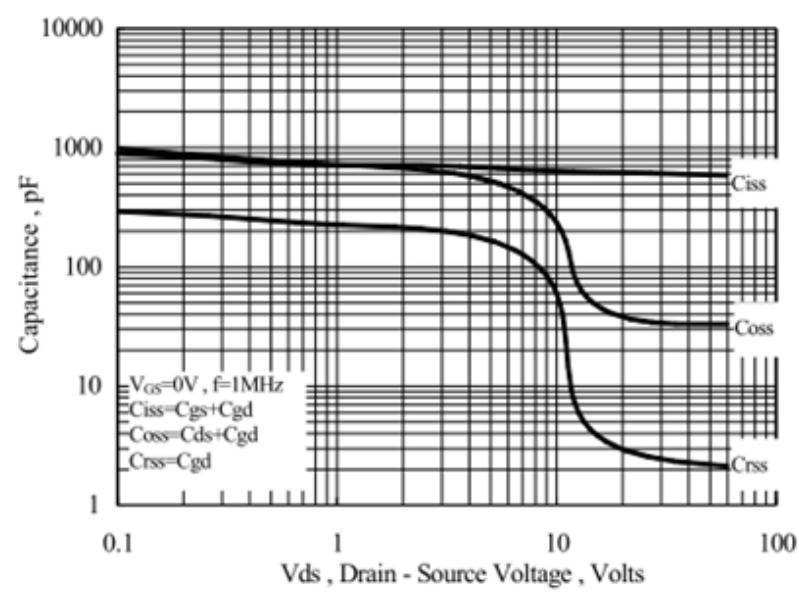


Figure 12 Typical Capacitance vs Drain to Source Voltage

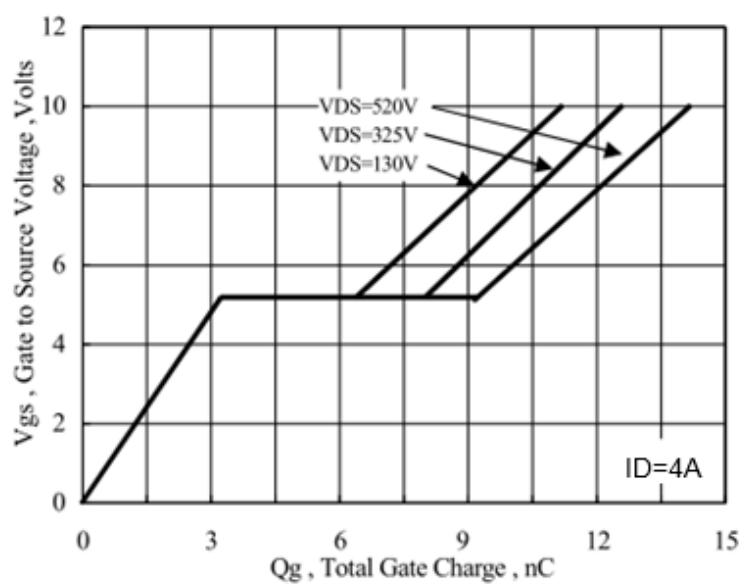
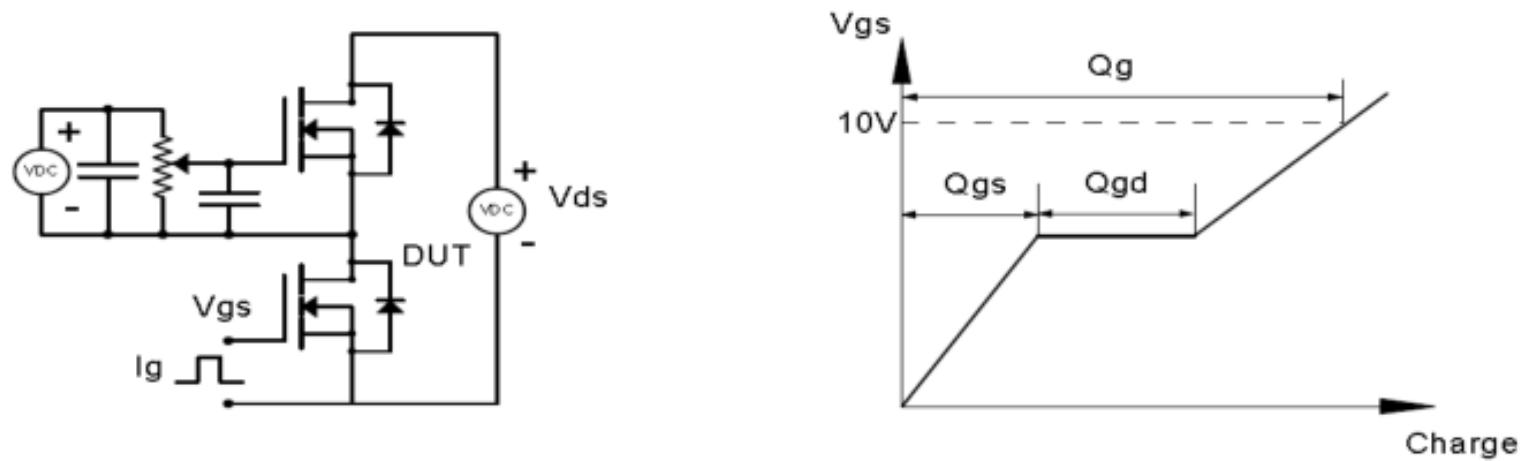


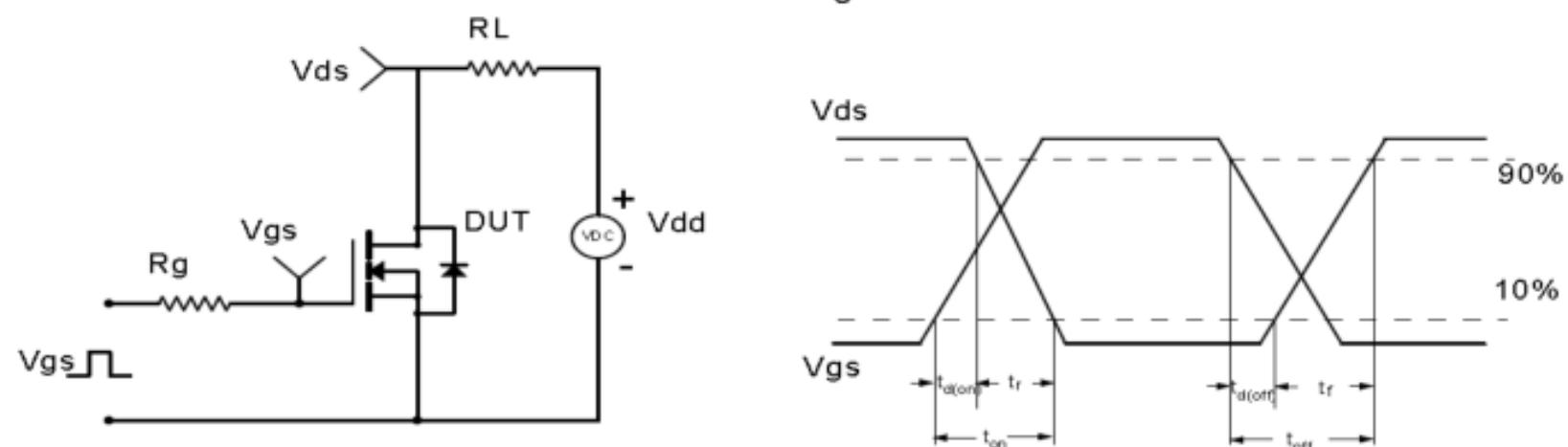
Figure 13 Typical Gate Charge vs Gate to Source Voltage

Test Circuit & Waveform

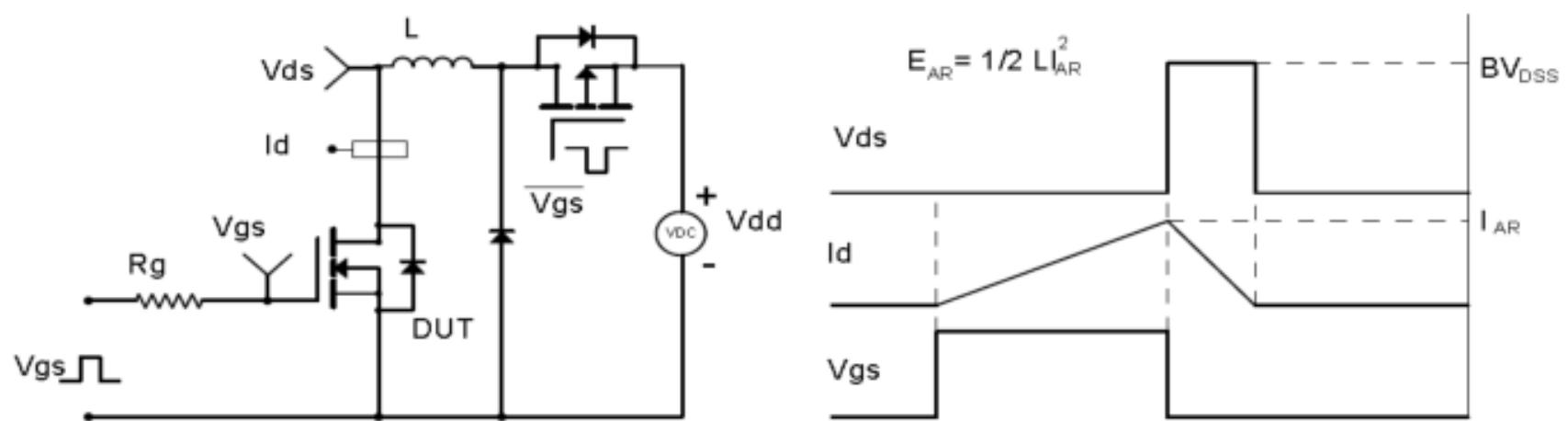
Gate Charge Test Circuit & Waveform



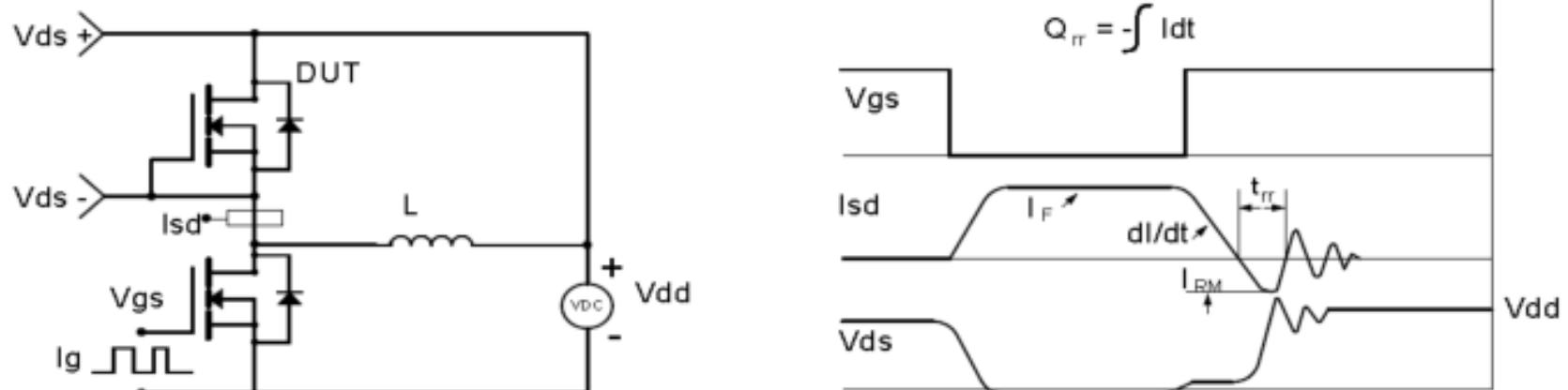
Resistive Switching Test Circuit & Waveforms



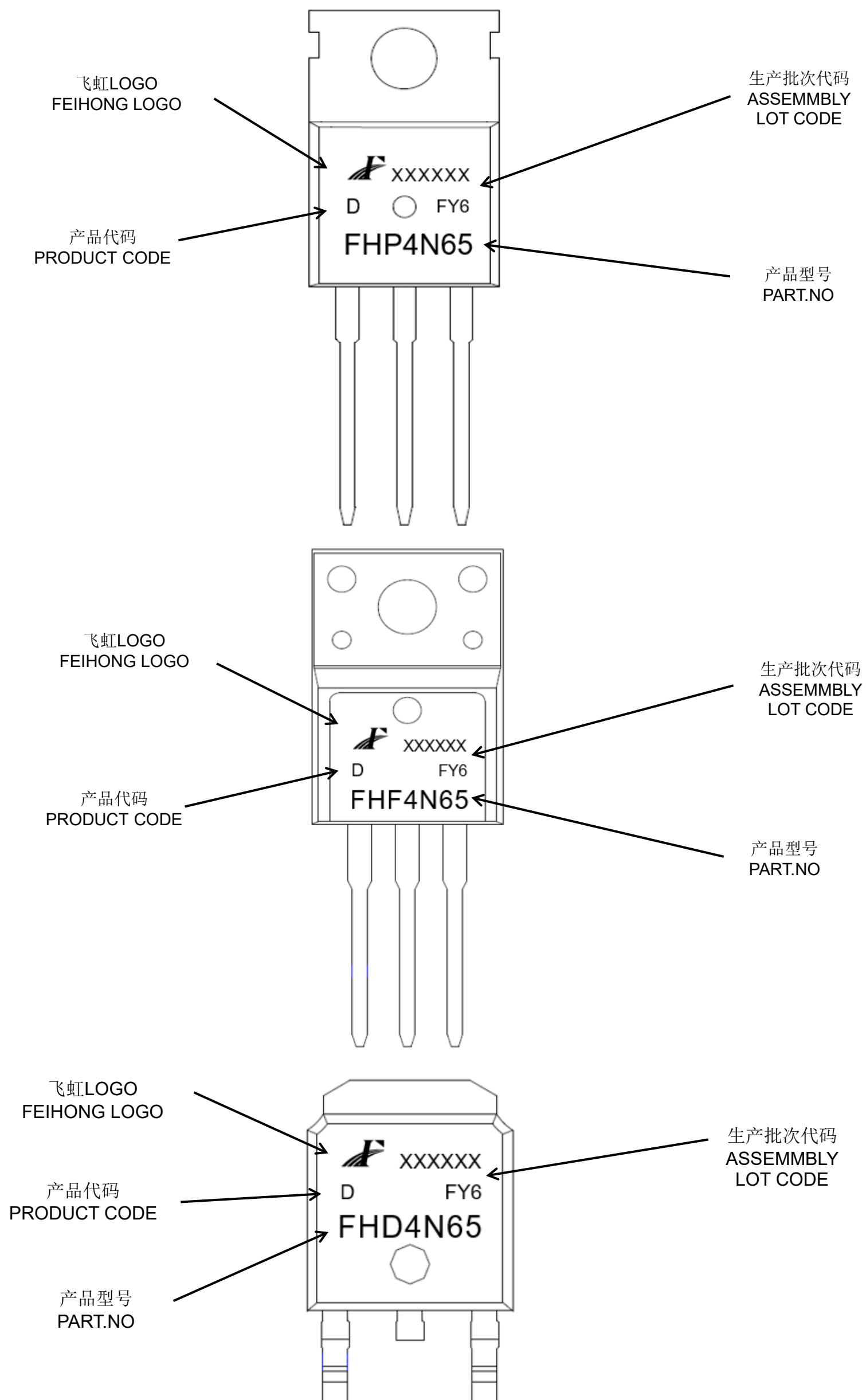
Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



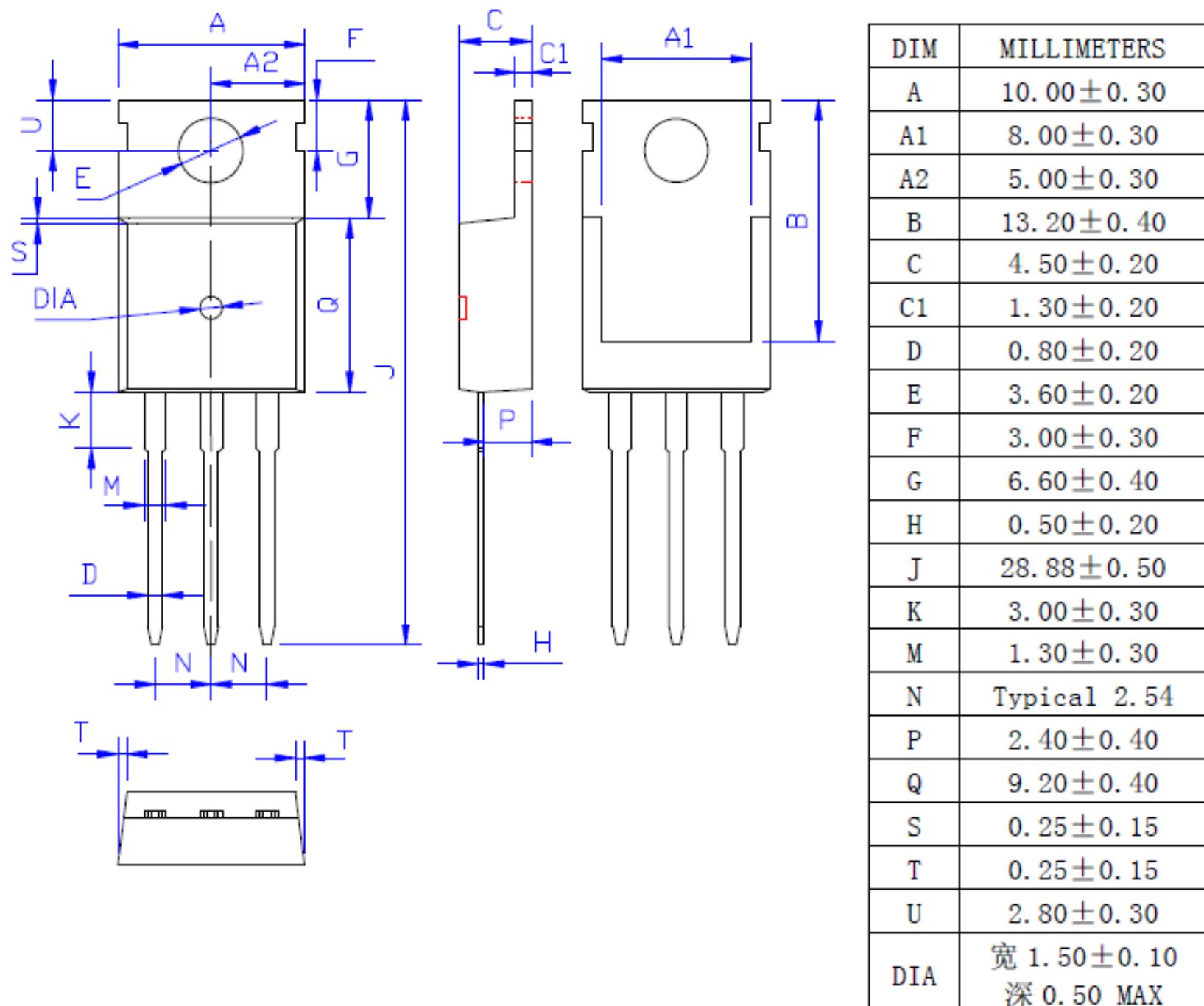
印记 Marking:



外形尺寸:

Package Dimension:

TO-220

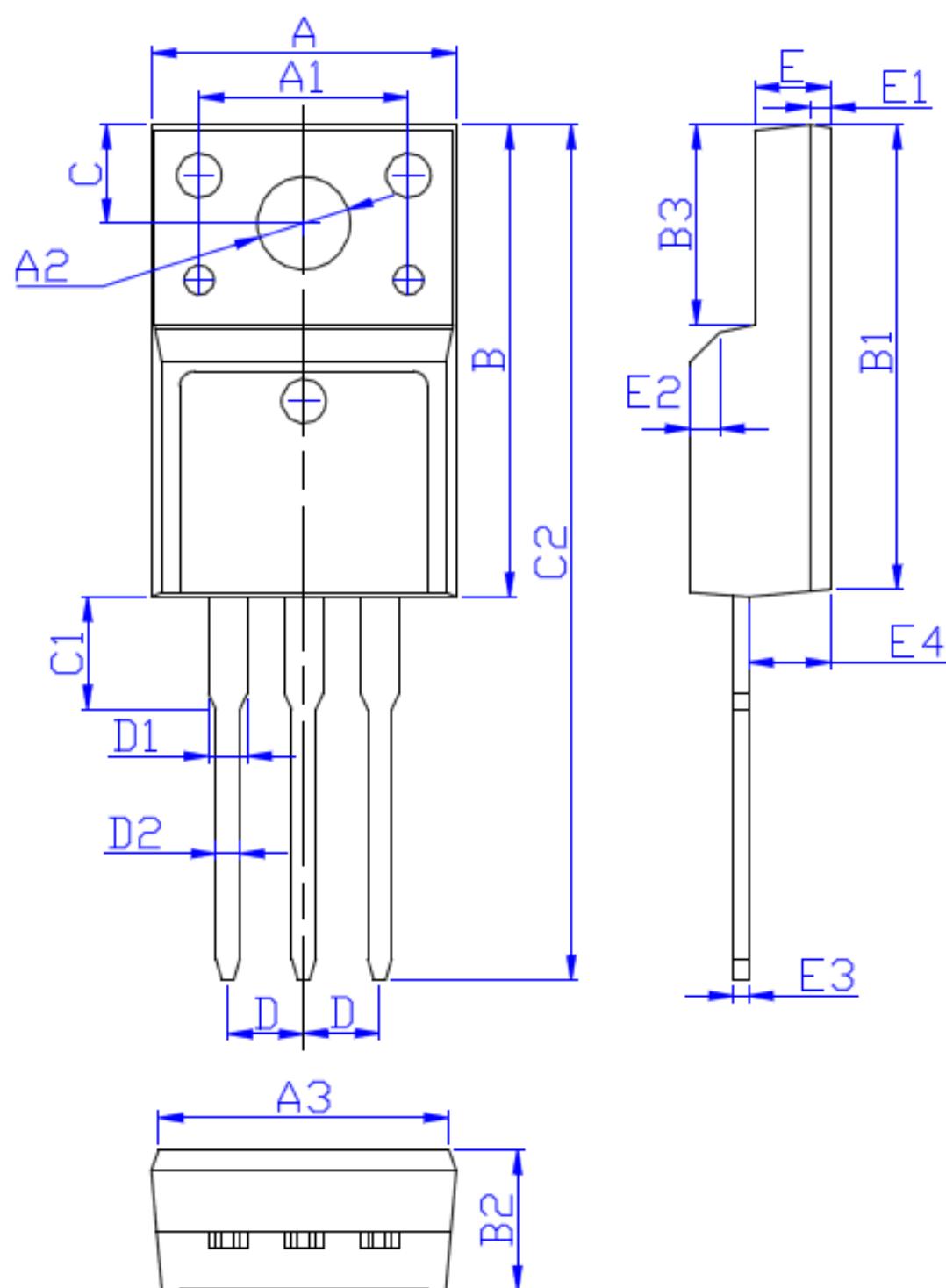


(Unit: mm)

外形尺寸:

Package Dimension:

TO-220F



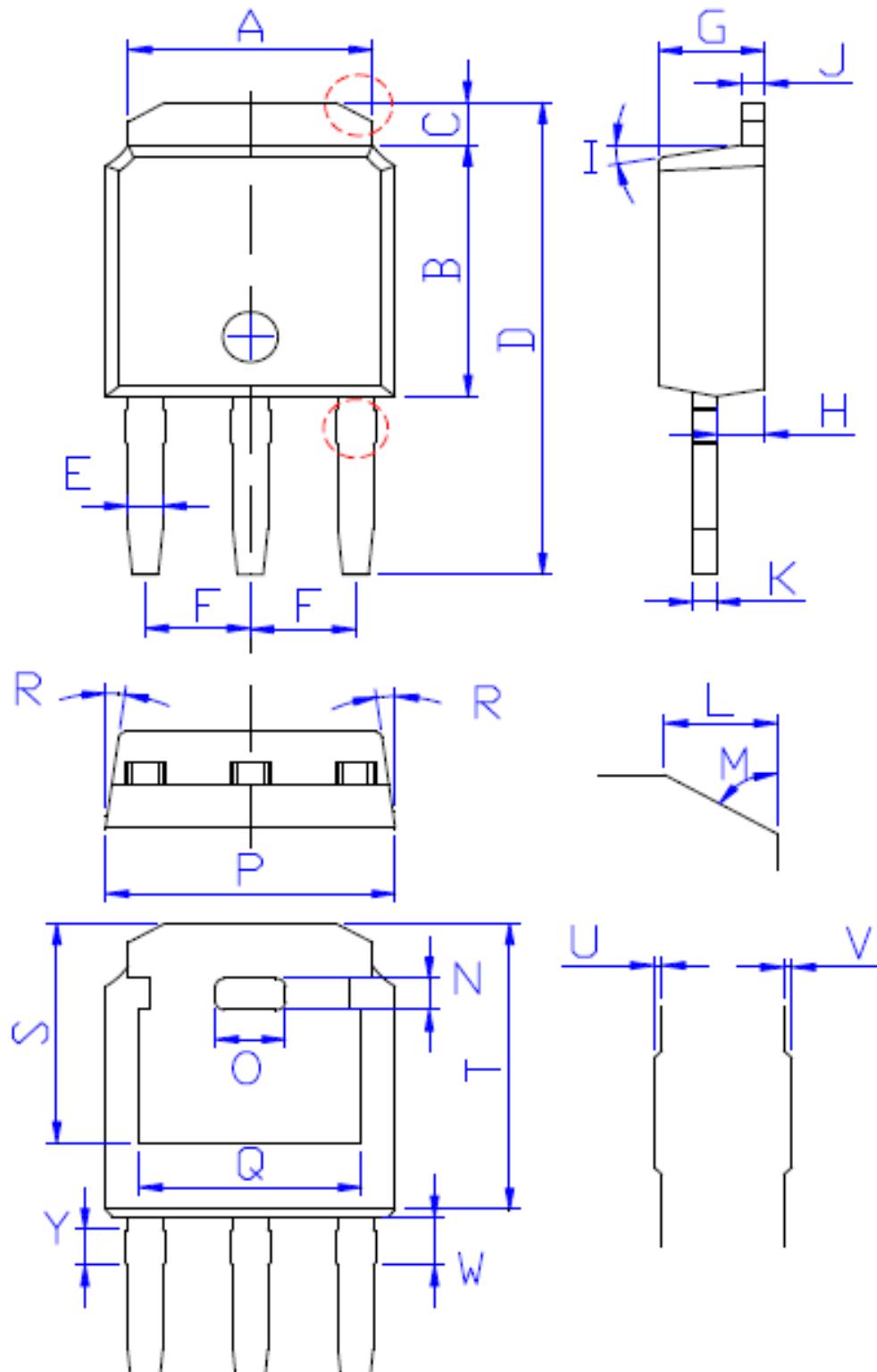
DIM	MILLIMETERS
A	10.16±0.30
A1	7.00±0.20
A2	3.12±0.20
A3	9.70±0.30
B	15.90±0.50
B1	15.60±0.50
B2	4.70±0.30
B3	6.70±0.30
C	3.30±0.25
C1	3.25±0.30
C2	28.70±0.50
D	Typical 2.54
D1	1.47 (MAX)
D2	0.80±0.20
E	2.55±0.25
E1	0.70±0.25
E2	1.0×45°
E3	0.50±0.20
E4	2.75±0.30

(Unit:mm)

外形尺寸：

Package Dimension:

TO-251



DIM	MILLIMETERS
A	5.34±0.30
B	6.00±0.30
C	1.05±0.30
D	11.31±0.30
E	0.76±0.15
F	2.28±0.15
G	2.30±0.30
H	1.06±0.30
I	(4-10)°
J	0.51±0.15
K	0.52±0.15
L	0.80±0.30
M	60°
N	0.75±0.30
O	1.80±0.30
P	6.60±0.30
Q	4.85±0.30
R	(4-8.5)°
S	5.30±0.30
T	6.90±0.30
U	0.05±0.05
V	0.05±0.05
W	1.15±0.25
Y	0.85±0.25

(Unit: mm)